ASSOCIATION CONNECTINI	Material Composition © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration	ion of the s encompasse	ubstances es all lower	within the manufactu r level materials for w	rer listed	item. Note: i nanufacturer	f the item is an as has engineering	sembly with lower responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia				ials and N	als and Mfg Information			
Supplier Inform	ation													
Company name*			Company unique ID			-	Unique ID Authority				Response Date*			
onsemi											2025-09-16			
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative				Phone - Representative*				Email - Representative*			
Product-Env-Stewa	rds	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requeste	ester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	ate Version Manufacturing Site			Weight*	UOM	Unit Type	
		NCP81381MNTXG I		Integrated Driver and MOSFET			2025-09-16		P	РНА		101.13	mg	Each
Manufacturing ]	Proccess Information	1												
Terminal Plating / Grid Array Material Terminal			erminal Base Alloy J-STD-020 MSL			L Rating	Peak Process Body Temperature Max Time at Pea			k Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU			U Alloy 3				260 C 30			seconds 3				
Comments														
ATTENTION: MSL	3 Rated item requires Ba	ake and D	ry Pack (after	electrical test)										
For more information	on regarding material con	position j	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Supplier Digital Signature	astislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.02	mg	Supplier	Silicon (Si)	7440-21-3		3.02	mg
Die Attach Solder	5.35	mg	Supplier	Silver (Ag)	7440-22-4		0.1338	mg
			А	Lead (Pb)	7439-92-1	7a	4.9488	mg
			Supplier	Tin (Sn)	7440-31-5		0.2675	mg
Lead Frame	59.54	mg	Supplier	Silver (Ag)	7440-22-4		0.9824	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0714	mg
			Supplier	Iron (Fe)	7439-89-6		1.3992	mg
			Supplier	Copper (Cu)	7440-50-8		57.0691	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0179	mg
Mold Compound-Black	31.34	mg	Supplier	Epoxy resins	129915-35-1		1.567	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.567	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1254	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.7208	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		26.639	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.7208	mg
Plating	1.57	mg	Supplier	Tin (Sn)	7440-31-5		1.57	mg
Wire Bond - Au	0.31	mg	Supplier	Gold (Au)	7440-57-5		0.31	mg